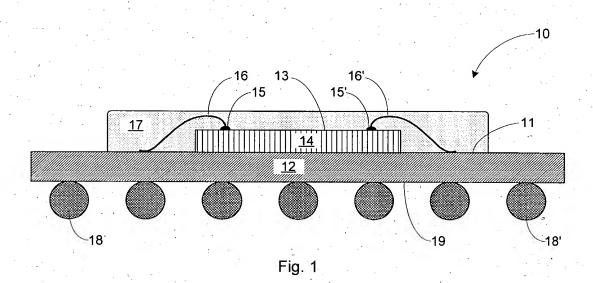
Inventor: Pendse
Title: Low Cost, High Performance Flip Chip
Package Structure
Attorney Docket: CPAC 1015-1
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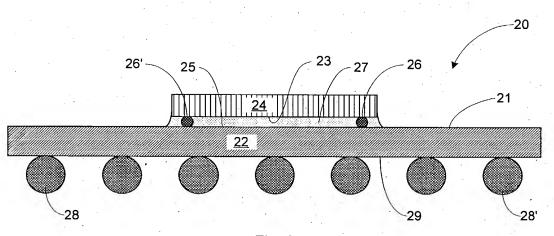


Fig. 2

Inventor: Pendse
Title: Low Cost, High Performance Flip Chip
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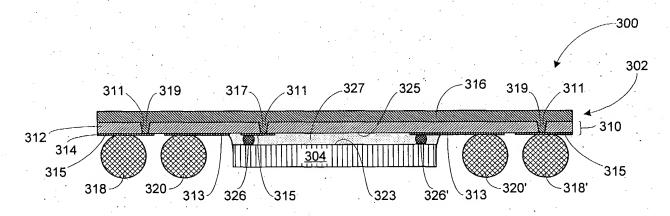


Fig. 3

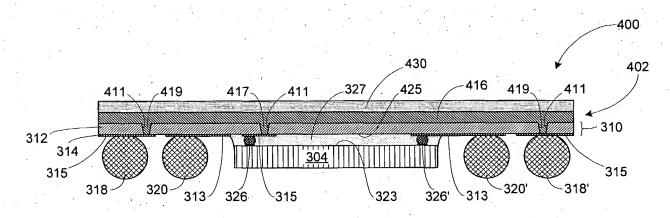


Fig. 4

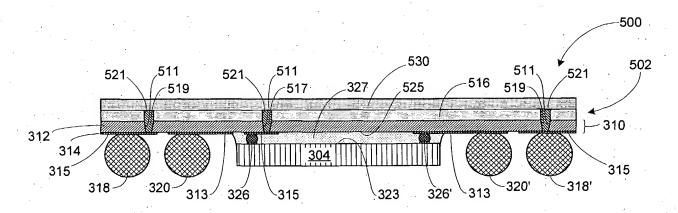


Fig. 5:

Inventor: Pendse
Title: Low Cost, High Performance Flip Chip
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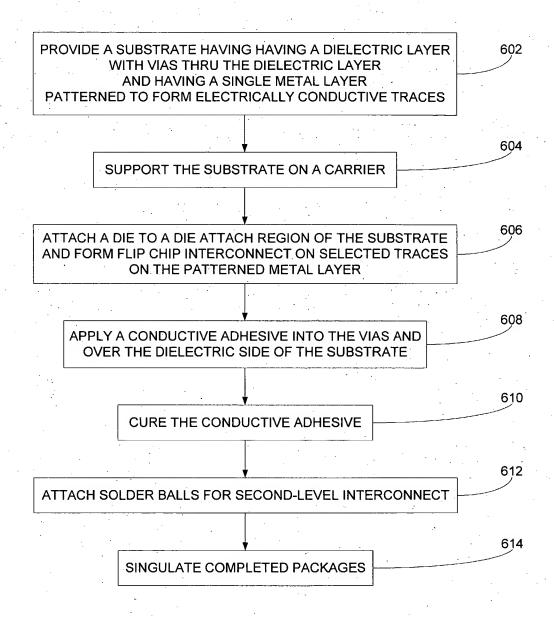


Fig. 6

Inventor: Pendse
Title: Low Cost, High Performance Flip Chip
Package Structure
Attorney Docket: CPAC 1015-1
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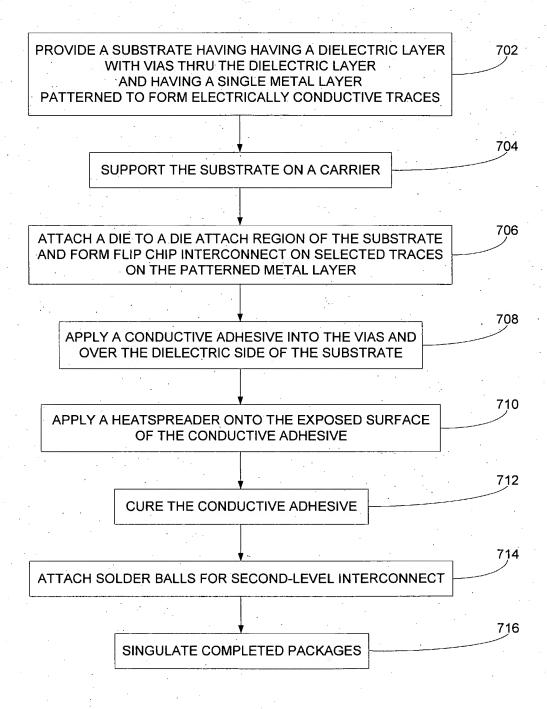


Fig. 7

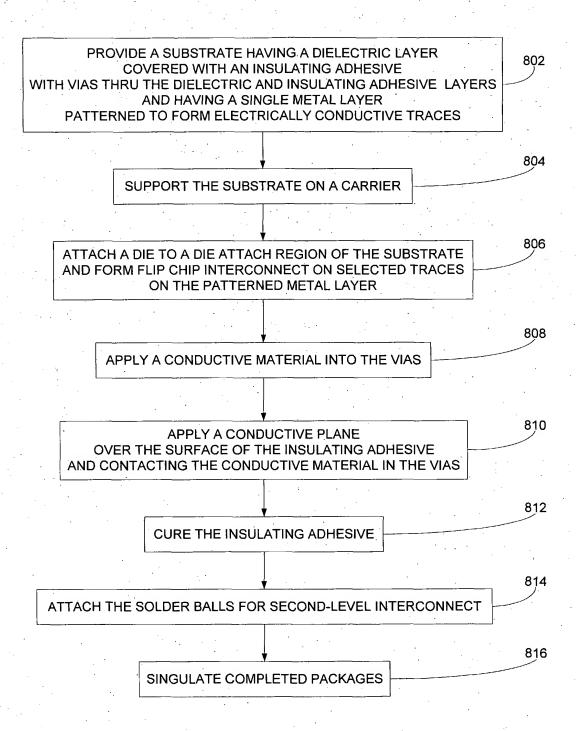


Fig. 8